AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended): A surface acoustic wave device comprising:

a piezoelectric substrate;

at least one IDT disposed on the piezoelectric substrate;

an input end and an output end connected to the IDT, at least one of the input end and the output end including a pair of balanced signal terminals; and

at least one of a delay line and a reactance component connected to one of the pair of balanced signal terminals; wherein

the delay line is used to improve the amplitude balance of the surface acoustic wave device; and

the reactance component is used to improve the phase balance of the surface acoustic wave device.

Claim 2 (original): A surface acoustic wave device according to claim 1, wherein the surface acoustic wave device is a longitudinally coupled resonator type surface acoustic wave filter in which at least three IDTs are disposed along the surface acoustic wave propagation direction.

Claim 3 (original): A surface acoustic wave device according to claim 2, wherein the surface acoustic wave device includes a plurality of the longitudinally coupled resonator type surface acoustic wave filters.

Claim 4 (original): A surface acoustic wave device according to claim 1, wherein there is no electrically neutral point between the first and second balanced signal terminals.

Claim 5 (original): A surface acoustic wave device according to claim 1, further comprising a package and a microstrip line provided on one of the package and the piezoelectric substrate, wherein the microstrip line constitutes at least one of the delay line and the reactance component.

Claim 6 (original): A surface acoustic wave device according to claim 5, further comprising a plurality of IDTs disposed on the piezoelectric substrate and housed inside the package such that the surface of the piezoelectric substrate having the IDTs disposed thereon facing downward.

Claim 7 (original): A surface acoustic wave device according to claim 1, further comprising a package having electrodes disposed thereon, wherein the electrodes of the package are electrically connected to at least one of the input and output ends having the first and second balanced signal terminals via a bonding wire, and wherein the bonding wire constitutes at least one of the delay line and the reactance component.

Claim 8 (original): A communication device containing a surface acoustic wave device according to claim 1.

Claim 9 (currently amended): A surface acoustic wave device comprising:

a piezoelectric substrate;

at least one IDT disposed on the piezoelectric substrate;

an input end and an output end connected to the IDT, at least one of the input end and the output end including a pair of balanced signal terminals; and

at least one of a plurality of delay lines and a plurality of reactance components connected to the pair of balanced signal terminals, respectively, and being different from each other; wherein

the delay line is used to improve the amplitude balance of the surface acoustic wave device; and

the reactance component is used to improve the phase balance of the surface acoustic wave device.

Claim 10 (original): A surface acoustic wave device according to claim 9, wherein the surface acoustic wave device is a longitudinally coupled resonator type surface acoustic wave filter in which at least three IDTs are disposed along the surface acoustic wave propagation direction.

Claim 11 (original): A surface acoustic wave device according to claim 10, wherein the surface acoustic wave device includes a plurality of the longitudinally coupled resonator type surface acoustic wave filters.

Claim 12 (original): A surface acoustic wave device according to claim 9, wherein there is no electrically neutral point between the first and second balanced signal terminals.

Claim 13 (original): A surface acoustic wave device according to claim 9, further comprising a package and a microstrip line provided on one of the package and the piezoelectric substrate, wherein the microstrip line constitutes at least one of the delay line and the reactance component.

Claim 14 (original): A surface acoustic wave device according to claim 13, further comprising a plurality of IDTs disposed on the piezoelectric substrate and

housed inside the package such that the surface of the piezoelectric substrate having the IDTs disposed thereon facing downward.

Claim 15 (original): A surface acoustic wave device according to claim 9, further comprising a package having electrodes disposed thereon, wherein the electrodes of the package are electrically connected to at least one of the input and output ends having the first and second balanced signal terminals via a bonding wire, and wherein the bonding wire constitutes at least one of the delay line and the reactance component.

Claim 16 (original): A communication device containing a surface acoustic wave device according to claim 9.

Claims 17-24 (canceled).

Claim 25 (new): A surface acoustic wave device according to claim 1, wherein the amplitude balance is less than about 0.75 dB.

Claim 26 (new): A surface acoustic wave device according to claim 1, wherein the phase balance is less than about 5°.

Claim 27 (new): A surface acoustic wave device according to claim 9, wherein the amplitude balance is less than about 0.75 dB.

Claim 28 (new): A surface acoustic wave device according to claim 9, wherein the phase balance is less than about 5°.